

WHAT IS CLAIMED IS:

1. A laminated ceramic electronic component comprising:

a laminated member including a plurality of stacked ceramic layers having a first ceramic layer and a second ceramic layer which is thinner than said first ceramic layer;

wiring conductors provided for a certain layer of said ceramic layers and including a via-hole conductor extending through said certain layer and a conductor extending along the principal surface of said certain layer; wherein

said via-hole conductor includes first and second via-hole conductors having different sectional sizes.

2. A laminated ceramic electronic component according to Claim 1, wherein said first via-hole conductor extends through said first ceramic layer, said second via-hole conductor extends through said second ceramic layer, and the sectional size of said first via-hole conductor is larger than that of said second via-hole conductor.

3. A laminated ceramic electronic component according to Claim 2, wherein, of all said via-hole conductors, the sectional size of the via-hole conductor extending through

the thicker ceramic layer is larger than that of the via-hole conductor extending through the thinner ceramic layer.

4. A laminated ceramic electronic component according to Claim 3, wherein a plurality of said via-hole conductors extending through the same ceramic layer have substantially the same sectional size.

5. A laminated ceramic electronic component according to Claim 2, wherein the aspect ratio expressed by H/D is within the range of approximately 0.1 to approximately 3.0, wherein H and D represent the height and radial length of said via-hole conductor, respectively.

6. A laminated ceramic electronic component according to Claim 1, wherein said plurality of ceramic layers have substantially the same dielectric constant.

7. A method for manufacturing a laminated ceramic electronic component, comprising the steps of:

preparing a plurality of ceramic green sheets including a first ceramic green sheet and a second ceramic green sheet that is thinner than said first ceramic green sheet;

forming through holes extending through at least said first and second ceramic green sheets;

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filling a conductive paste into said through holes so as to form via-hole conductors therein;

obtaining a green laminated member by stacking said ceramic green sheets including said first and second ceramic green sheets; and

sintering said green laminated member;

wherein the sectional size of a first through hole formed through said first ceramic green sheet is larger than that of a second through hole formed through said second ceramic green sheet.

8. The method according to claim 7, wherein the via-hole conductors include a first via-hole conductor extending through said first ceramic sheet and a second via-hole conductor extending through said second ceramic sheet, and the sectional size of said first via-hole conductor is larger than that of said second via-hole conductor.

9. The method according to claim 8, wherein of all said via-hole conductors, the sectional size of the via-hole conductor extending through the first ceramic sheet is larger than that of the via-hole conductor extending through the second ceramic sheet.

10. The method according to claim 9, wherein a

plurality of said via-hole conductors extending through the same ceramic layer have substantially the same sectional size.

11. The method according to claim 8, wherein the aspect ratio expressed by  $H/D$  is within the range of approximately 0.1 to approximately 3.0, wherein  $H$  and  $D$  represent the height and radial length of said via-hole conductor, respectively.

12. The method according to Claim 7, wherein said plurality of ceramic layers have substantially the same dielectric constant.

13. An electronic device comprising:

- a laminated ceramic electronic component; and
- a wiring board for mounting said laminated ceramic electronic component thereon;

wherein said laminated ceramic electronic component includes a laminated member having a plurality of stacked ceramic layers including a first ceramic layer and a second ceramic layer that is thinner than said first ceramic layer;

wherein wiring conductors are provided for a specific ceramic layer and include a via-hole conductor extending through said specific ceramic layer and a conductor film

extending along the principal surface of said specific ceramic layer; and

    said via-hole conductor includes first and second via-hole conductors having different sectional sizes.

14. An electronic device according to Claim 13, wherein said first via-hole conductor extends through said first ceramic layer, said second via-hole conductor extends through said second ceramic layer, and the sectional size of said first via-hole conductor is larger than that of said second via-hole conductor.

15. An electronic device according to Claim 14, wherein, of all said via-hole conductors, the sectional size of the via-hole conductor extending through the thicker ceramic layer is larger than that of the via-hole conductor extending through the thinner ceramic layer.

16. An electronic device according to Claim 15, wherein a plurality of said via-hole conductors extending through the same ceramic layer have substantially the same sectional size.

17. An electronic device according to Claim 14, wherein the aspect ratio expressed by  $H/D$  is within the range of

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approximately 0.1 to approximately 3.0, wherein H and D represent the height and radial length of said via-hole conductor, respectively.

18. An electronic device according to Claim 14, wherein said plurality of ceramic layers have substantially the same dielectric constant.

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